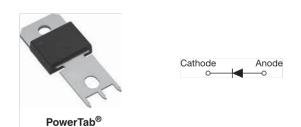


Vishay Semiconductors

# Ultrafast Soft Recovery Diode, 150 A FRED Pt®



PRODUCT SUMMARY				
Package	PowerTab <sup>®</sup>			
I <sub>F(AV)</sub>	150 A			
$V_{R}$	400 V			
V <sub>F</sub> at I <sub>F</sub>	0.9 V			
t <sub>rr</sub> (typ.)	See recovery table			
T <sub>J</sub> max.	175 °C			
Diode variation	Single die			

#### **FEATURES**

- Ultrafast recovery time
- 175 °C max. operating junction temperature
- Screw mounting only
- Designed and qualified according to JEDEC®-JESD 47









#### **BENEFITS**

- Reduced RFI and EMI
- Higher frequency operation
- · Reduced snubbing
- · Reduced parts count

#### **DESCRIPTION / APPLICATIONS**

These diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems.

The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for HF welding, power converters and other applications where switching losses are not significant portion of the total losses.

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Cathode to anode voltage	V <sub>R</sub>		400	V
Continuous forward current	I <sub>F(AV)</sub>	T <sub>C</sub> = 104 °C	150	
Single pulse forward current	I <sub>FSM</sub>	T <sub>C</sub> = 25 °C	1500	Α
Maximum repetitive forward current	I <sub>FRM</sub>	Square wave, 20 kHz	300	
Operating junction and storage temperatures	T <sub>J</sub> , T <sub>Stg</sub>		-55 to +175	°C

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	BOL TEST CONDITIONS		TYP.	MAX.	UNIT
Breakdown voltage, blocking voltage	$V_{BR}$ , $V_{R}$	$I_{R} = 200 \ \mu A$	400	-	-	
Forward voltage		I <sub>F</sub> = 150 A	-	1.07	1.3	V
	V <sub>F</sub>	I <sub>F</sub> = 150 A, T <sub>J</sub> = 175 °C	-	0.9	1.1	, v
		I <sub>F</sub> = 150 A, T <sub>J</sub> = 125 °C	-	0.96	1.17	
Reverse leakage current	I <sub>R</sub>	$V_R = V_R$ rated	-	-	50	μΑ
		T <sub>J</sub> = 150 °C, V <sub>R</sub> = V <sub>R</sub> rated	-	-	4	mA
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 400 V	-	100	-	рF
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from package body	-	3.5	-	nH



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<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
		$I_F = 1.0 \text{ A}, dI_F/dt = 200 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		-	-	60	
Reverse recovery time	Reverse recovery time t <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	93	-	ns
	T <sub>J</sub> = 125 °C		-	172	-		
Peak recovery current I <sub>RRM</sub>		T <sub>J</sub> = 25 °C	$I_F = 150 \text{ A}$	-	11	-	_
	T <sub>J</sub> = 125 °C	$V_R = 200 \text{ V}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$	-	20	-	Α	
Reverse recovery charge Q <sub>rr</sub>		T <sub>J</sub> = 25 °C		-	490	-	0
	T <sub>J</sub> = 125 °C		-	1740	-	nC	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	DL TEST CONDITIONS		TYP.	MAX.	UNITS
Thermal resistance, junction to case	R <sub>thJC</sub>		-	-	0.35	K/W
Thermal resistance, junction to heatsink	R <sub>thCS</sub>	Mounting surface, flat, smooth and greased	-	0.2	-	, wv
Weight			-	-	5.02	g
vveignt			-	0.18	-	oz.
Mounting torque			1.2 (10)	-	2.4 (20)	N · m (lbf · in)
Marking device		Case style PowerTab®		150E	BU04	

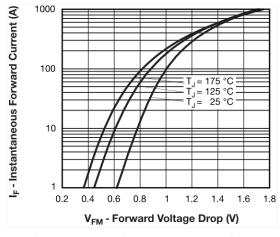


Fig. 1 - Maximum Forward Voltage Drop Characteristics

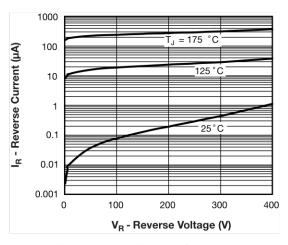


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage



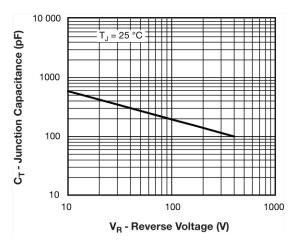


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

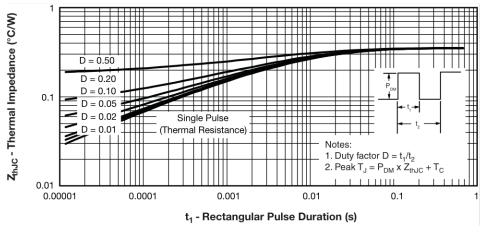


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics

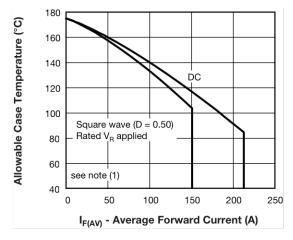


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

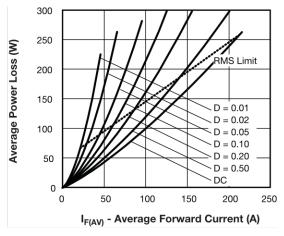


Fig. 6 - Forward Power Loss Characteristics

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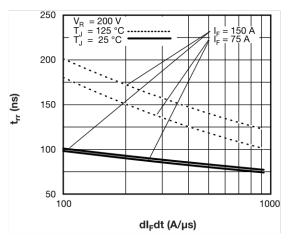


Fig. 7 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt

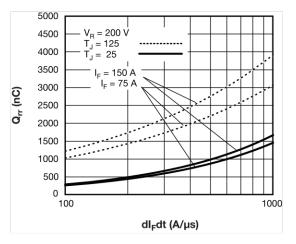


Fig. 8 - Typical Stored Charge vs. dl<sub>F</sub>/dt

#### Note

 $\begin{array}{ll} \text{(1)} & \text{Formula used: } T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}; \\ Pd = \text{Forward power loss} = I_{F(AV)} \times V_{FM} \text{ at } (I_{F(AV)}/D) \text{ (see fig. 6);} \\ Pd_{REV} = \text{Inverse power loss} = V_{R1} \times I_R \text{ (1 - D); } I_R \text{ at } V_{R1} = \text{Rated } V_R \\ \end{array}$ 

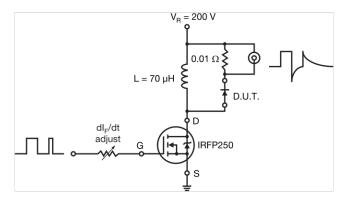


Fig. 9 - Reverse Recovery Parameter Test Circuit

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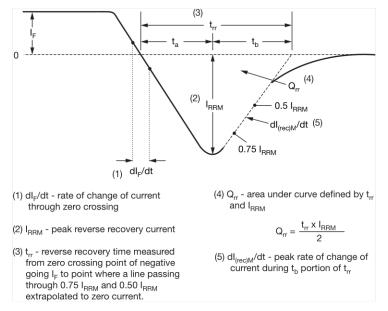
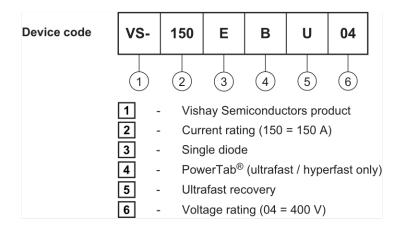


Fig. 10 - Reverse Recovery Waveform and Definitions

#### **ORDERING INFORMATION TABLE**



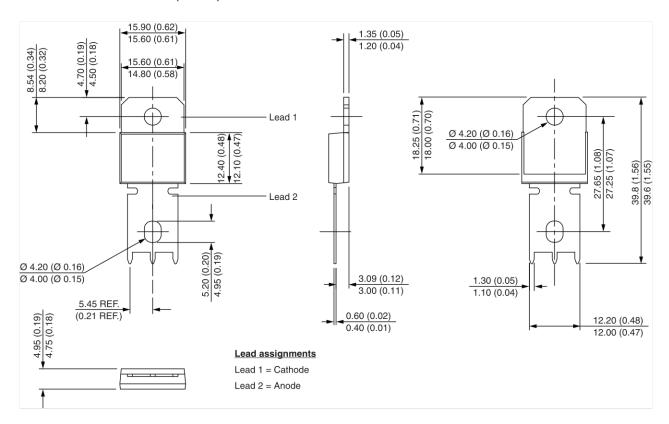
LINKS TO RELATED DOCUMENTS				
Dimensions <u>www.vishay.com/doc?95240</u>				
Part marking information	www.vishay.com/doc?95370			
Application note	www.vishay.com/doc?95179			
SPICE model	www.vishay.com/doc?95623			



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### PowerTab<sup>®</sup>

### **DIMENSIONS** in millimeters (inches)





## **Legal Disclaimer Notice**

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